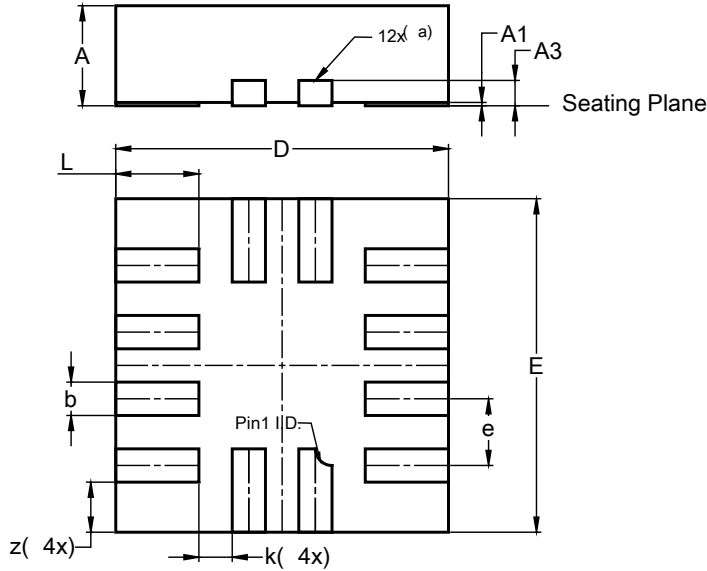


**Package Outline Dimensions**

U-QFN2020-12 (Type C)

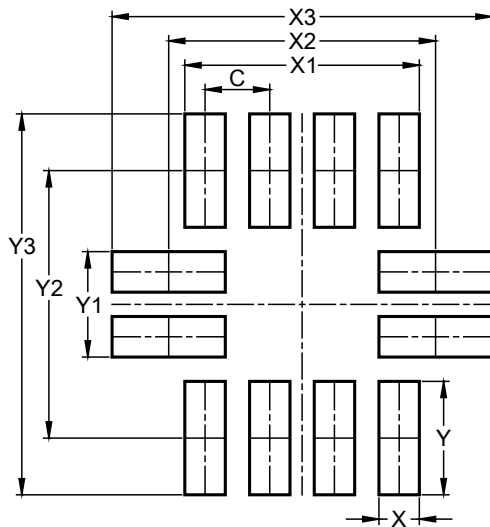


Note ( a ) Actual shape dependent upon the manufacturing technology used.

U-QFN2020-12 (Type C)			
Dim	Min	Max	Typ
A	0.55	0.65	0.60
A1	0.00	0.05	0.02
A3	--	--	0.152
b	0.15	0.25	0.20
D	1.95	2.05	2.00
E	1.95	2.05	2.00
e	0.40 BSC		
L	0.45	0.55	0.50
k	--	--	0.20
z	--	--	0.30
All Dimensions in mm			

**Suggested Pad Layout**

U-QFN2020-12 (Type C)



Dimensions	Value (in mm)
C	0.400
X	0.250
X1	1.450
X2	1.650
X3	2.350
Y	0.700
Y1	0.650
Y2	1.650
Y3	2.350

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.